| ASSOCIATION CONNECTING LECTRONICS INDUSTRIES | ckburn, Illinois, A | Ill rights reserved untions. | under both | This docume level parts, t | ent is a declarati he declaration e | on of the su | bstances s all lower | within the manufactur level materials for w | rer listed i hich the n | tem. Note: nanufacture | if the item is an as er has engineering | sembly with lower responsibility. | |
|---|---|------------------------------|--------------|-------------------------------|---|-----------------|----------------------|--|---------------------------------|---------------------------------|--|-----------------------------------|--|
| | IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute | | | k | Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials | | | | | s and Mfg Information | | | |
| Supplier Information | | | | | | | | | | | | | |
| mpany name* Company unique ID | | | Unique I | | | ue ID Authority | | | Respons | Response Date* | | | |
| onsemi | | | | | | | | | 2023-06-07 | | | | |
| Contact Name | Title - Contact | | |] | Phone - Contact* | | | | Email - Contact* | | | | |
| oduct-Env-Stewards Product Enviro Compliance | | | | | NA | | | | Product-Env-Stewards@onsemi.com | | | | |
| uthorized Representative* Title - Representative | | | |] | Phone - Representative* | | | | Email - Representative* | | | | |
| Product-Env-Stewards Product Enviro C | | | o Compliance | | | NA | | | | Product-Env-Stewards@onsemi.com | | | |
| Requester Item Number Mfr 1 | tem Number | Mfr Item Name | | | Effective Date | Version | Ν | Manufacturing Site | | Weight* | UOM | Unit Type | |
| NCV G | 3570BMN330R2 200MA ULN RF L | | LDO REG3.3V | | 2023-06-07 | | N | MY1 | | 20.0 | mg | Each | |
| Manufacturing Proccess Information | | | | | | | | | | | | | |
| Terminal Plating / Grid Array Material | Terminal Base | Ferminal Base Alloy J-S | | Rating | Peak Process Body Temp | | emperatur | ature Max Time at Peak T | | ure Num | ber of Reflow Cyc | les | |
| Matte Tin (Sn) - annealed | atte Tin (Sn) - annealed CU Alloy | | 1 | 260 | | С | | 30 secon | | seconds 3 | | | |
| Comments | | | | | | | | | | | | | |
| level 1 - maximum time at peak temperature during | soldering is 10-3 | 0 seconds | | | | | | | | | | | |
| For more information regarding material composit | on please refer to | page 3 | | | | | | | | | | | |

| RoHS Material Composition Declaration | | | | Declaration Type * | Detailed | | | | | |
|--|---|--|---|---|---|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS Directive 2011/65/EU | RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl ohthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP). | | | | | | | | | |
| cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a | ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the | henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies | RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform | ce of its products with European Union membe | ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of | | | | | |
| RoHS Declaration * 1 - Item(s) | does not contain RoHS restricted substa | on above | Supplier Acceptance | * Accepted | | | | | | |
| Exemption: If the declared item does not con applicable exemptions. | ntain RoHS restricted substances per | the definition above | except for defined RoHS exempti | ons, then select the corresponding response i | n the RoHS Declaration above and choose all | | | | | |
| Exemption List Version | EL-2011/534/EU | | | | | | | | | |
| Declaration Signature | | | | | | | | | | |
| Instructions: Complete all of the required fin Requester) and click on Submit Form to have | elds on all pages of this form. Select the form returned to the Requester | he "Accepted" on th | e Supplier Acceptance drop-down | . This will display the signature area. Digital | lly sign the declaration (if required by the | | | | | |
| Supplier Digital Signature Ra | stislav Drska | Le | | | | | | | | |

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight | Unit of Measure | Level | Substance | CAS | Exempt | Weight | Unit of Measure |
|----------------------|--------|-----------------|----------|-------------------------|------------------|--------|--------|-----------------|
| Die | 0.2 | mg | Supplier | Silicon (Si) | 7440-21-3 | | 0.2 | mg |
| Die Attach | 0.45 | mg | Supplier | Silver (Ag) | 7440-22-4 | | 0.3375 | mg |
| | | | Supplier | Epoxy resins | 129915-35-1 | | 0.1125 | mg |
| Lead Frame 6.97 | 6.97 | mg | Supplier | Silver (Ag) | 7440-22-4 | | 1.9446 | mg |
| | | | Supplier | Iron (Fe) | 7439-89-6 | | 0.0767 | mg |
| | | | Supplier | Copper (Cu) | 7440-50-8 | | 4.9487 | mg |
| Mold Compound-Black | 10.0 | mg | | Epoxy resin | proprietary data | | 0.7 | mg |
| | | | Supplier | Phenolic Resin | Proprietary Data | | 0.7 | mg |
| | | | Supplier | Silica Amorphous (SiO2) | 7631-86-9 | | 1.5 | mg |
| | | | Supplier | Carbon Black (C) | 1333-86-4 | | 0.05 | mg |
| | | | Supplier | Fused Silica (SiO2) | 60676-86-0 | | 7.05 | mg |
| Plating | 0.71 | mg | Supplier | Tin (Sn) | 7440-31-5 | | 0.71 | mg |
| Wire Bond - Au | 1.67 | mg | Supplier | Gold (Au) | 7440-57-5 | | 1.67 | mg |